

HOSTAFORM® C 13021 XAP®2

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POM copolymer Medium flow injection molding grade with reduced emissions especially for automotive interior application.
Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Emission according to VDA 275 < 2 mg/kg (natural grades) Emission according to VDA 275 < 5 mg/kg (colored grades)

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	12 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	
Moulding shrinkage, parallel	2.0 %	ISO 294-4, 2577
Moulding shrinkage, normal	1.8 %	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2750 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	64 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9 %	ISO 527-1/-2
Nominal strain at break	25 %	ISO 527-1/-2
Flexural modulus	2700 MPa	ISO 178
Tensile creep modulus, 1h	2400 MPa	ISO 899-1
Tensile creep modulus, 1000h	1200 MPa	ISO 899-1
Charpy impact strength, 23°C	200 kJ/m ²	ISO 179/1eU
Charpy impact strength, -30°C	200 kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23°C	6.5 kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30°C	6 kJ/m ²	ISO 179/1eA
Poisson's ratio	0.37 ^[C]	

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166 °C	ISO 11357-1/-3
Coefficient of linear thermal expansion (CLTE), parallel	120 E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	120 E-6/K	ISO 11359-1/-2

Flammability

FMVSS Class	B	ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	44.7 mm/min	ISO 3795 (FMVSS 302)

Electrical properties

Relative permittivity, 100Hz	4	IEC 62631-2-1
Relative permittivity, 1MHz	4	IEC 62631-2-1
Dissipation factor, 100Hz	20 E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50 E-4	IEC 62631-2-1
Volume resistivity	1E12 Ohm.m	IEC 62631-3-1
Surface resistivity	1E14 Ohm	IEC 62631-3-2

HOSTAFORM® C 13021 XAP®2

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Electric strength	35 kV/mm	IEC 60243-1
Comparative tracking index	600	IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1410 kg/m³	ISO 1183

Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	190 °C
Min. melt temperature	180 °C
Max. melt temperature	200 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	4 MPa

Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Special characteristics	Low emissions

Additional information

Processing Notes

Pre-Drying

recommended

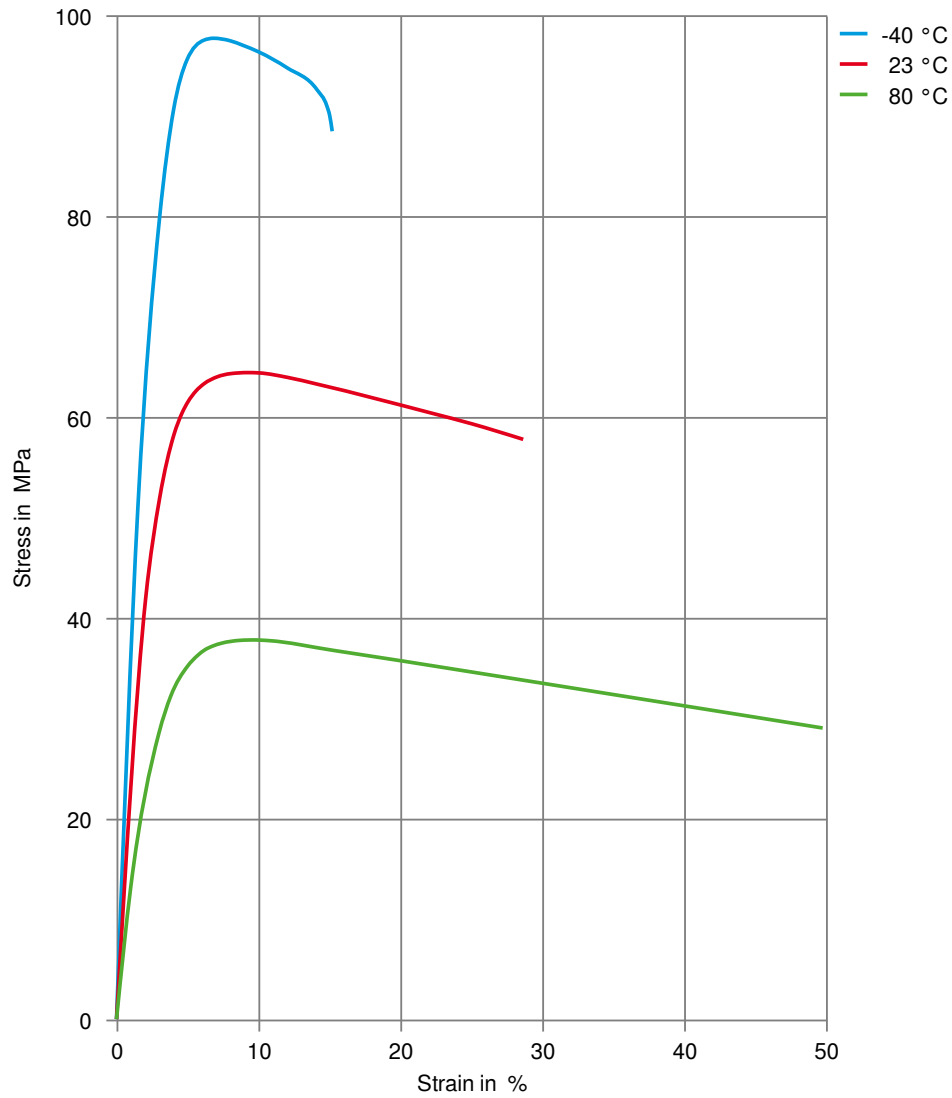
Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Mercedes-Benz	DBL5404	BQF
VW Group	TL 524 76	

HOSTAFORM® C 13021 XAP®2

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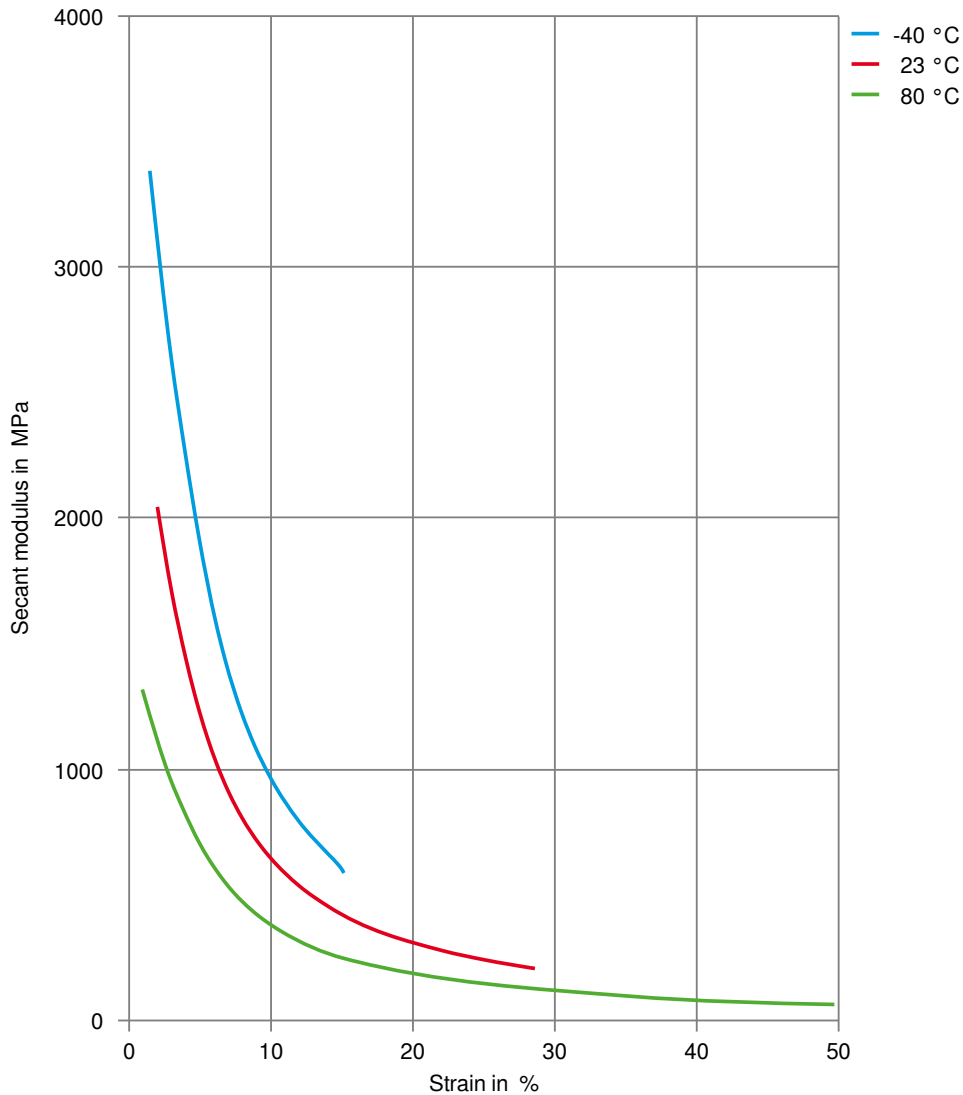
Stress-strain



HOSTAFORM® C 13021 XAP®2

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Secant modulus-strain



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Page: 4 of 4

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